

SEMICONDUCTOR DEVICE WITH STACK OF SEMICONDUCTOR CHIPS

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ABSTRACT OF THE DISCLOSURE

A semiconductor device is configured of a first semiconductor chip mounted on a substrate, a plate member arranged on the first semiconductor chip, and a second semiconductor chip arranged on the plate member. Bonding wires electrically connect the pads of the first semiconductor chip and the pads of the second semiconductor chip to the pads of the substrate, and a sealing resin seals the first semiconductor chip and the second semiconductor chip. A first portion of the plate member is displaced away from the ends of the first and second semiconductor chips, and a second portion of the plate member extending perpendicular to the first portion, projects outward from the first and second semiconductor chips to be exposed to the outside.

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